BAW56TT1G

Dual Switching Diode

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Reverse Voltage	V _R	70	Vdc
Forward Current	١ _F	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (Note 1), T _A = 25°C Derated above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	, Junction-to-Ambient R _{0JA} 555		°C/W
Total Device Dissipation, FR-4 Board (Note 2), T _A = 25°C Derated above 25°C	P _D	360 2.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)			°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

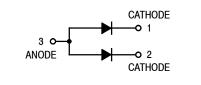
1. FR-4 @ Minimum Pad

2. FR-4 @ 1.0×1.0 Inch Pad



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CASE 463 SC-75/SOT-416 STYLE 4

MARKING DIAGRAM



A1 = Specific Device Code M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

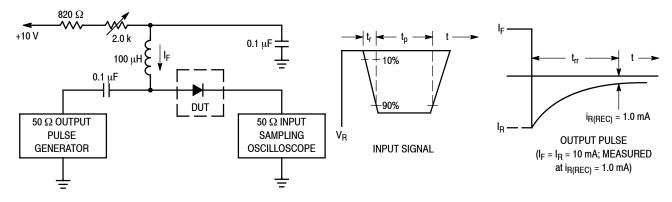
Device	Package	Shipping [†]		
BAW56TT1G	SC-75/SOT-416 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAW56TT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

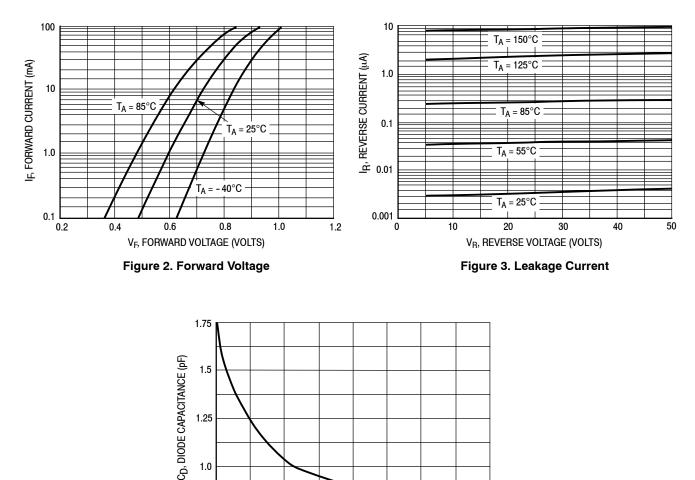
Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage (I _(BR) = 100 μAdc)	V _(BR)	70	-	Vdc
Reverse Voltage Leakage Current ($V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C}$) ($V_R = 70 \text{ Vdc}$) ($V_R = 70 \text{ Vdc}, T_J = 150^{\circ}\text{C}$)	I _R	- - -	30 2.5 50	μAdc
Diode Capacitance (V _R = 0, f = 1.0 MHz)	CD	-	2.0	pF
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 60 \text{ mAdc})$ $(I_F = 150 \text{ mAdc})$	VF	- - -	715 855 1000 1250	mVdc
Reverse Recovery Time (I _F = I _R = 10 mAdc, R _L = 100 Ω , I _{R(REC)} = 1.0 mAdc) (Figure 1)	t _{rr}	-	6.0	ns



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA. 3. t_p » t_{rr}



BAW56TT1G



1.25

1.0

0.75

r(t), NORMALIZED TRANSIENT THERMAL RESISTANCE

1.0

0.1

0.01

0.001

D = 0.5

0.2

0.1

0.05

0.02

0.01

0.00001

0

0.001

Ħ

0.0001

SINGLE PULSE

2

0.01

6

1.0

8

10

100

1000

4

V_R, REVERSE VOLTAGE (VOLTS) Figure 4. Capacitance

t, TIME (s) Figure 5. Normalized Thermal Response

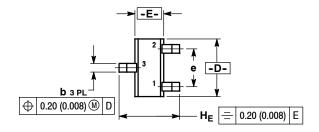
0.1

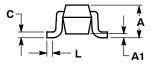


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PACKAGE DIMENSIONS

SC-75/SOT-416 CASE 463-01 ISSUE F





NOTES:

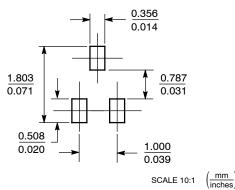
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
С	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.059	0.063	0.067
Е	0.70	0.80	0.90	0.027	0.031	0.035
е	1.00 BSC			0.04 BSC		
L	0.10	0.15	0.20	0.004	0.006	0.008
HE	1.50	1.60	1.70	0.061	0.063	0.065

STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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